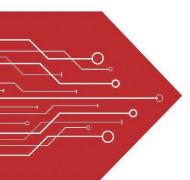
# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Product data sheet

www.msksemi.com

Semiconductor

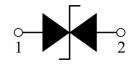
Compiance

#### **Specification Features**

Small Body Outline Dimensions: nom 0.039" x 0.024" (1.0x0.6 mm)

- Low Body Height: nom 0.0 19" (0.5 mm)
- Low Capacitance 15 pF
- Low Clamping Voltage
- Reverse Working (Stand-off) Voltage: 5V
- Low Leakage
- Response Time is Typically < 1 ns
- IEC61000-4-2 Level 4 ESD Protection
- This is a Pb-Free Device

**Pin Description** 



**Schematic Diagram** 

DFN1006P2X

#### **Mechanical Characteristics:**

- CASE: Void-free, transfer-molded, thermosetting plastic Epoxy Meets UL 94 V-0
- LEAD FINISH: NiPdAu
- MOUNTING POSITION: Any
- QUALIFIED MAX REFLOW TEMPERATURE: 260°C
- Device Meets MSL 1 Requirements
- RoHS/WEEE Compliant
- Marking: Marking code

#### **Applications**

- Cellular Handsets & Accessories
- Personal Digital Assistants (PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- MP3 Players

#### **ELECTRICAL CHARACTERISTICS**

P/N	V <sub>RWM</sub> (V)	I <sub>R1</sub> (μΑ) @ V <sub>RWM</sub>	I <sub>R2</sub> (μ <b>A)</b> @ V <sub>R</sub> =3.5V	V <sub>BR</sub> (V (Not		lτ	V <sub>C</sub> (V) @ I <sub>PP</sub> = 1 A (Note 3)	V <sub>C</sub> (V) @MAX I <sub>PP</sub> (Note 3)	<b>IPP(A)</b> (Note 3)	Ppk(W) (Note 3)	C (pF)
P/N	Max	Max	Max	Min	Max	mA	Max	Max	Max	Max	Max
AZ5725-01F-MS	5.0	0.5	0.3	5.6	8.0	1.0	9.8	12.5	5.5	69	15

#### **Maximum Ratings**

maximum radingo					
Rating	Symbol	Value	Unit		
IEC 61000-4-2 (ESD) Contact		±30	kV		
Peak Power Per 8 x 20µs Waveform	P <sub>PK</sub>	70	W		
Total Power Dissipation on FR-5 <sup>®</sup> Board @ TA = 25°C	P <sub>D</sub>	300	mW		
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Lead Solder Temperature - Maximum (10 Second Duration)	T∟	260	°C		





Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
I <sub>T</sub>	Test Current
$V_{BR}$	Breakdown Voltage @ I⊤

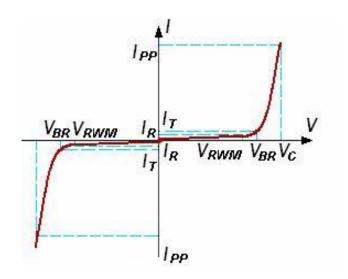


FIG1: Pulse Waveform

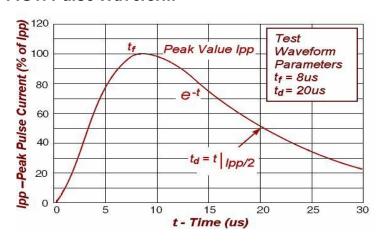
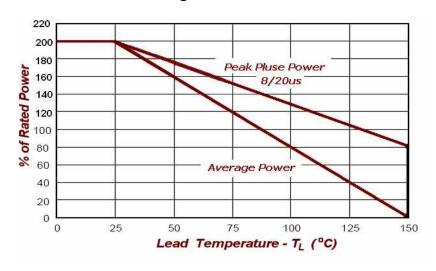


FIG2:Power Derating

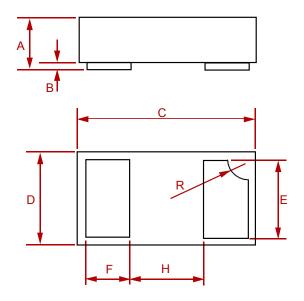






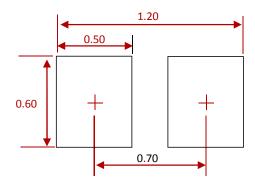


### **PACKAGE MECHANICAL DATA**



Dim	Inc	hes	Millimeters		
Dim	MIN MAX		MIN	MAX	
А	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.01	5Тур.	0.40Typ.		
R	0.001	0.005	0.05	0.15	

## **Suggested Pad Layout**



#### NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

### **REEL SPECIFICATION**

P/N	PKG	QTY
AZ5725-01F-MS	DFN1006P2X	10000



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